



Click [here](#) for the 3D model.

#### General Information

|                          |                                                                  |
|--------------------------|------------------------------------------------------------------|
| Series                   | ESD SMD Comm COG                                                 |
| Style                    | SMD Chip                                                         |
| Description              | SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I |
| Features                 | Temperature Stable, Low ESR, Class I                             |
| RoHS                     | Yes                                                              |
| Termination              | Flexible Termination                                             |
| Marking                  | No                                                               |
| AEC-Q200                 | No                                                               |
| Typical Component Weight | 15 mg                                                            |
| Shelf Life               | 78 Weeks                                                         |
| MSL                      | 1                                                                |

#### Specifications

|                                                                    |                        |
|--------------------------------------------------------------------|------------------------|
| Capacitance                                                        | 1,000 pF               |
| Measurement Condition                                              | 1 MHz 1.0Vrms          |
| Capacitance Tolerance                                              | 20%                    |
| Voltage DC                                                         | 200 VDC                |
| ESD Level per AEC-Q200                                             | 12,000 V ESD Level     |
| Dielectric Withstanding Voltage                                    | 500 VDC                |
| Temperature Range                                                  | -55/+125°C             |
| Temperature Coefficient                                            | COG                    |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor                                                 | 0.1% 1 MHz 1.0Vrms     |
| Aging Rate                                                         | 0% Loss/Decade Hour    |
| Insulation Resistance                                              | 100 GOhms              |

#### Dimensions

|           |                  |
|-----------|------------------|
| Chip Size | 1206             |
| L         | 3.3mm +/-0.4mm   |
| W         | 1.6mm +/-0.35mm  |
| T         | 0.78mm +/-0.20mm |
| S         | 1.5mm MIN        |
| B         | 0.6mm +/-0.25mm  |

#### Packaging Specifications

|                    |           |
|--------------------|-----------|
| Packaging          | Bulk, Bag |
| Packaging Quantity | 1         |

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